



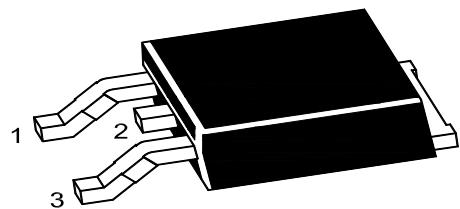
PJM10H45NTE

N-Channel Enhancement Mode Power MOSFET

Features

- Excellent package for good heat dissipation
- High density cell design for ultra low $R_{DS(on)}$
- $V_{DS} = 100V, I_D = 45A$
- $R_{DS(on)} < 20m\Omega @ V_{GS} = 10V$

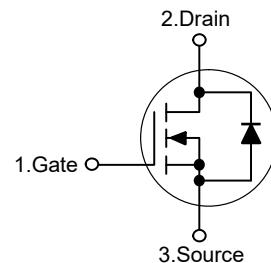
TO-252



1. Gate 2.Drain 3.Source
Schematic Diagram

Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



		Marking code										
		10H45: Product code										
Y: Year code	%\$<45 YW	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	
		G	H	J	K	A	B	C	D	E	F	
W: Week code	Weeks			1~26			27~52			53		
	code			A~Z			a~z			z		

Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	45	A
Drain Current-Pulsed ^{Note1}	I_{DM}	180	A
Single pulse avalanche energy ^{Note4}	E_{AS}	81	mJ
Maximum Power Dissipation $T_c=25^\circ C$	P_D	72	W
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Thermal Characteristics

Thermal Resistance, Junction-to-Ambient ^{Note2}	$R_{\theta JA}$	50	°C/W
Maximum Junction-to-Case ^{Note2}	$R_{\theta JC}$	1.73	°C/W



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Electrical Characteristics

($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	100	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
Gate Threshold Voltage ^{Note3}	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.8	2.5	V
Drain-Source On-Resistance ^{Note3}	$R_{DS(\text{on})}$	$V_{GS}=10\text{V}, I_D=20\text{A}$	--	14	20	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=10\text{A}$	--	18	25	$\text{m}\Omega$
Forward Transconductance ^{Note3}	g_{FS}	$V_{DS}=5\text{V}, I_D=3\text{A}$	--	15	--	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=30\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	1135	--	pF
Output Capacitance	C_{oss}		--	399	--	pF
Reverse Transfer Capacitance	C_{rss}		--	18	--	pF
Gate Resistance	R_g	$V_{DS}=0\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	0.6	--	Ω
Switching Characteristics						
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD}=50\text{V}, I_D=25\text{A}$ $V_{GS}=10\text{V}, R_{\text{GEN}}=2.2\Omega$	--	39.2	--	nS
Turn-on Rise Time	t_r		--	11	--	nS
Turn-off Delay Time	$t_{d(\text{off})}$		--	53.2	--	nS
Turn-off Fall Time	t_f		--	15.8	--	nS
Total Gate Charge	Q_g	$V_{DS}=50\text{V}, I_D=25\text{A}, V_{GS}=10\text{V}$	--	16	--	nC
Gate-Source Charge	Q_{gs}		--	5.6	--	nC
Gate-Drain Charge	Q_{gd}		--	2.4	--	nC
Source-Drain Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{SD}	$V_{GS}=0\text{V}, I_s=20\text{A}$	--	0.9	1.3	V
Diode Forward Current ^{Note2}	I_s		--	--	45	A

Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

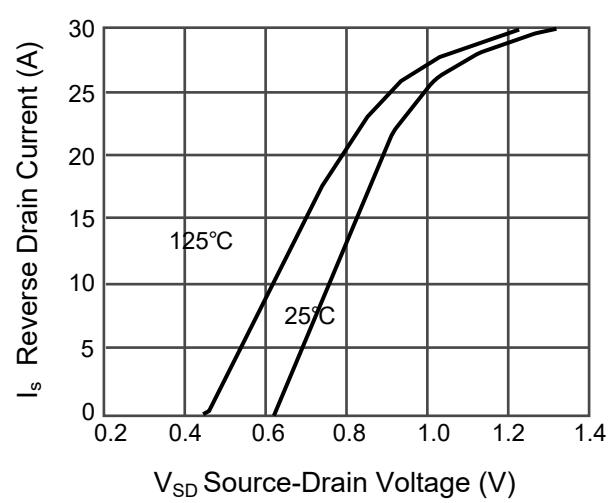
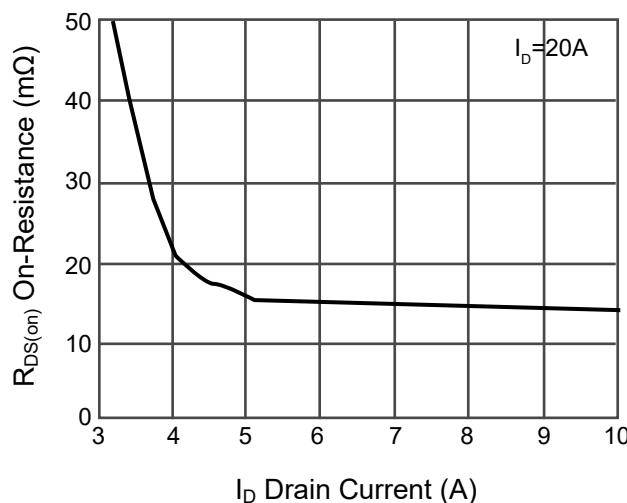
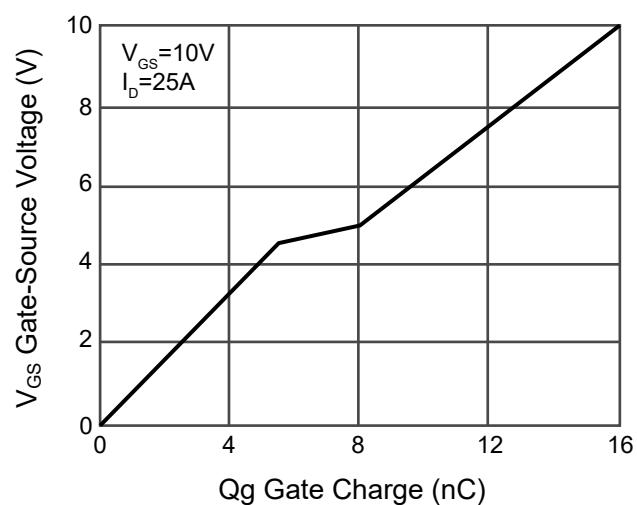
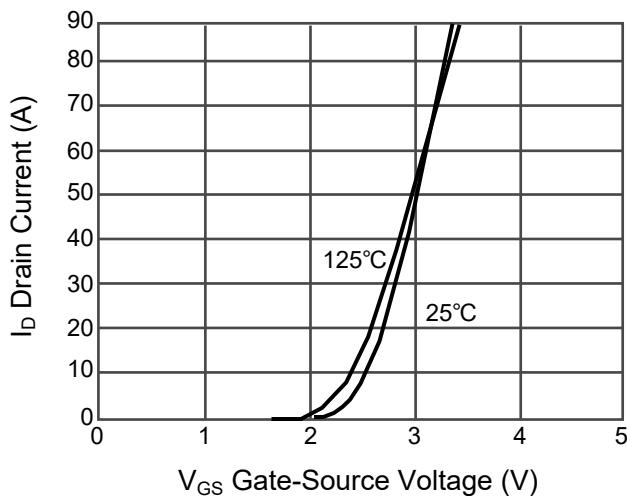
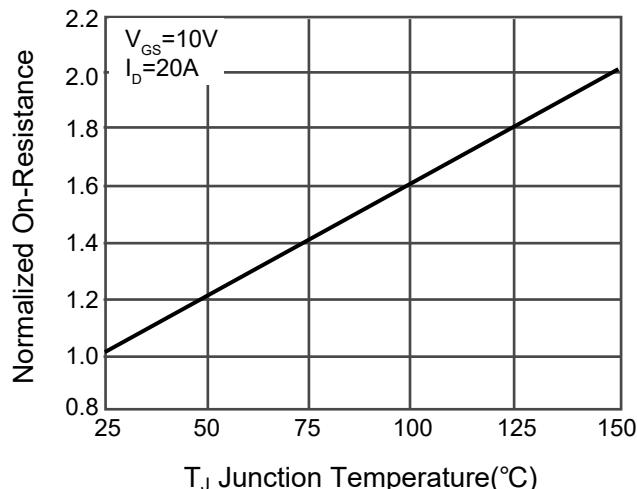
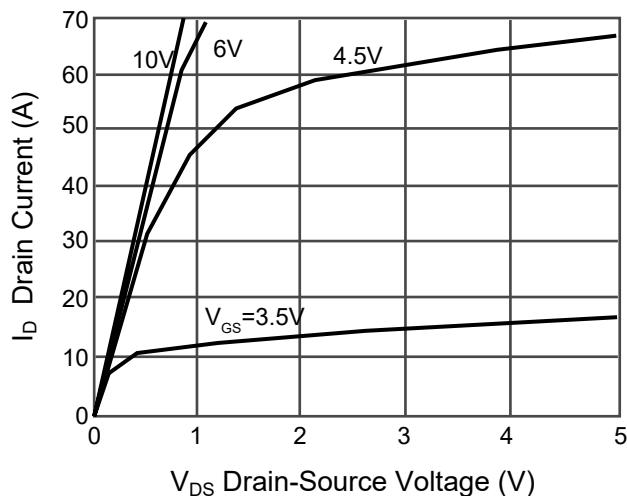
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The Power dissipation PDSM is based on $R_{\theta JA} t \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. E_{AS} condition : $T_j=25^\circ\text{C}, V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}, R_G=25\Omega, I_{AS}=15\text{A}$.



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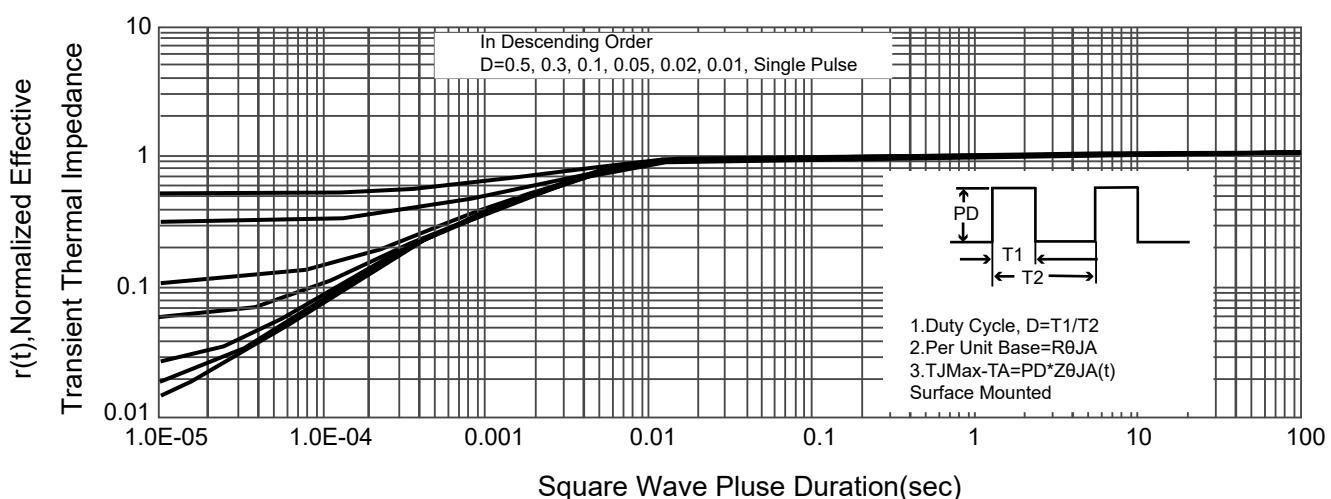
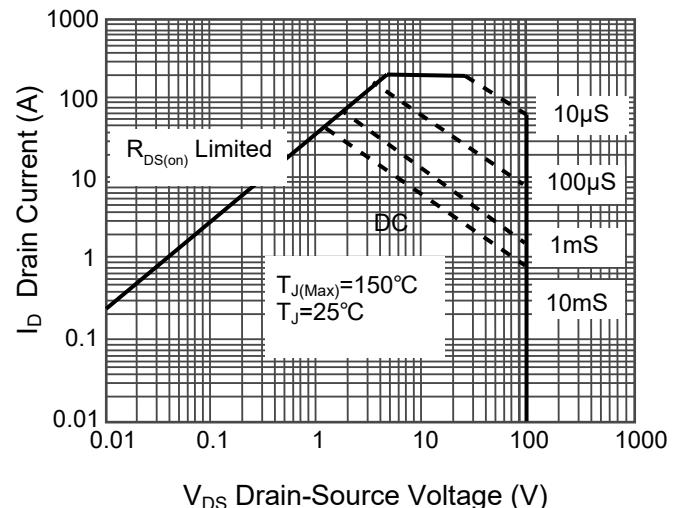
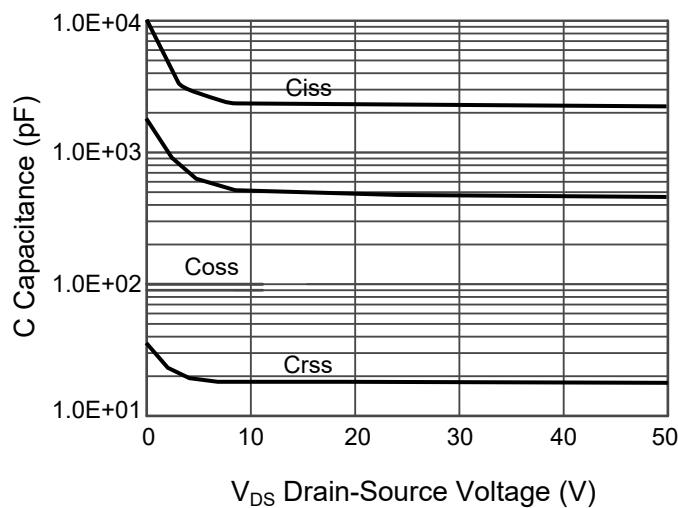
Typical Characteristic Curves





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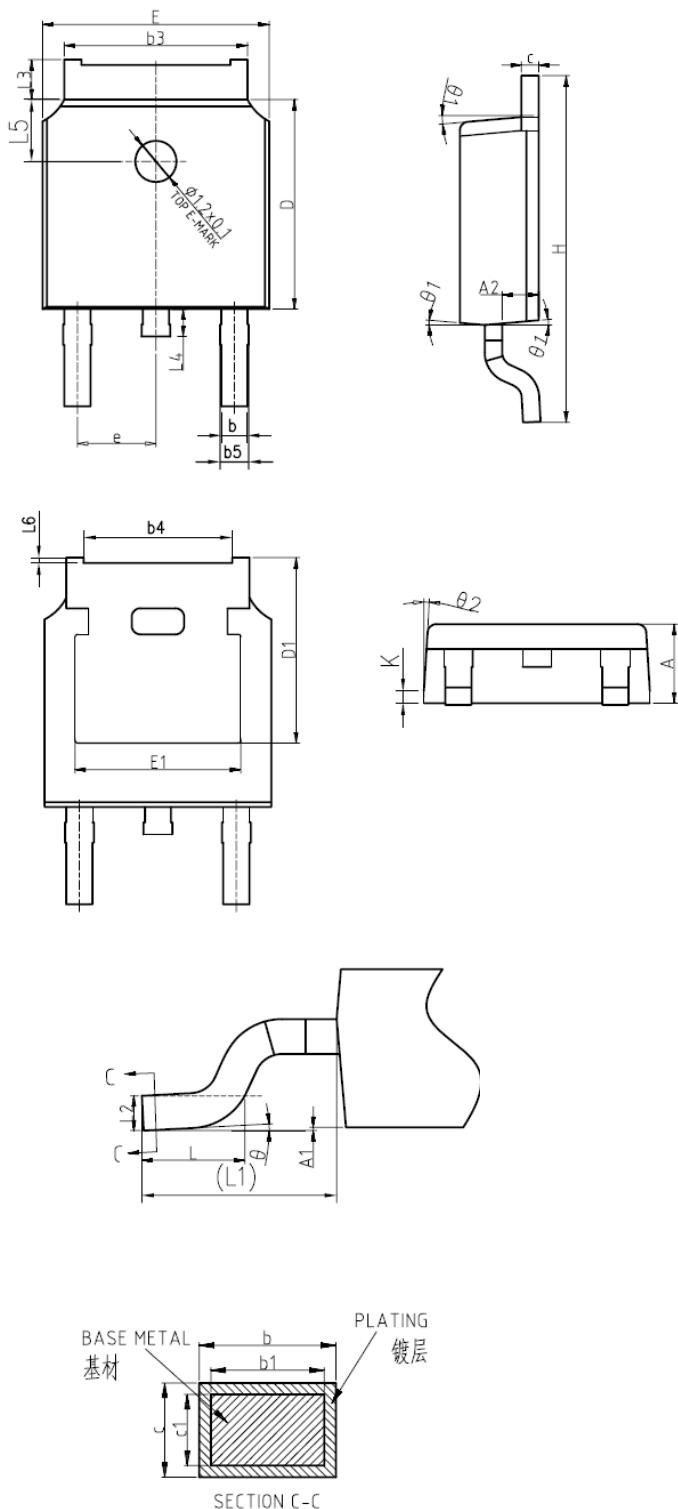
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Package Outline

TO-252

Dimensions in mm



Symbol	mm		
	Min.	Nom.	Max.
*A	2.20	2.30	2.38
*A1	0.00	--	0.10
A2	0.97	1.07	1.17
*b	0.72	0.78	0.85
b1	0.71	0.76	0.81
*b3	5.23	5.33	5.46
b4	4.27	4.32	4.37
b5	0.72	0.88	0.93
*c	0.47	0.53	0.58
c1	0.46	0.51	0.56
*D	6.00	6.10	6.20
D1	5.30REF		
*E	6.50	6.60	6.70
E1	4.70	4.83	4.92
*e	2.286BSC		
*H	9.90	10.10	10.30
L	1.40	1.50	1.70
L1	2.90REF		
L2	0.51BSC		
*L3	0.90	--	1.25
*L4	0.60	0.80	1.00
L5	1.70	1.80	1.90
L6	0	0.047	0.123
θ	0°	--	8°
*θ1	5°	7°	9°
θ2	5°	7°	9°
K	0.40REF		

带*为检验尺寸

Ordering Information

Device	Package	Shipping
PJM10H45NTE	TO-252	2,500PCS/Reel&13inches